



FPGA/ASIC supply-chain thematic

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Head of Marketing & Sales

Who is NanoXplore?

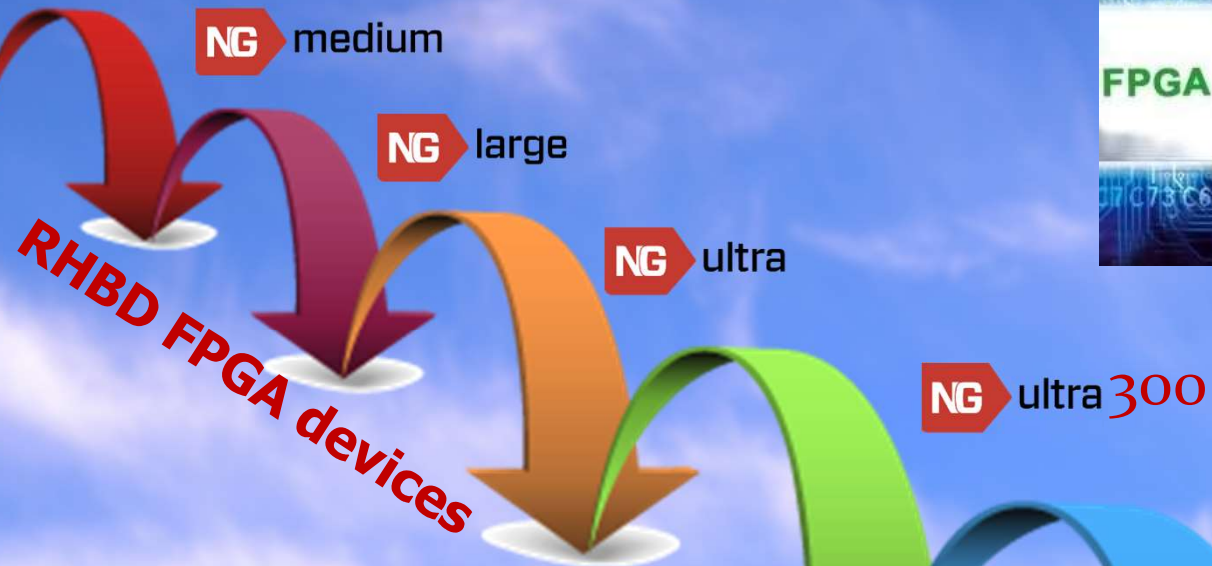


NX ITAR-free PLD vendor

- ◆ NanoXplore is the EU solution for Programmable Logic Devices

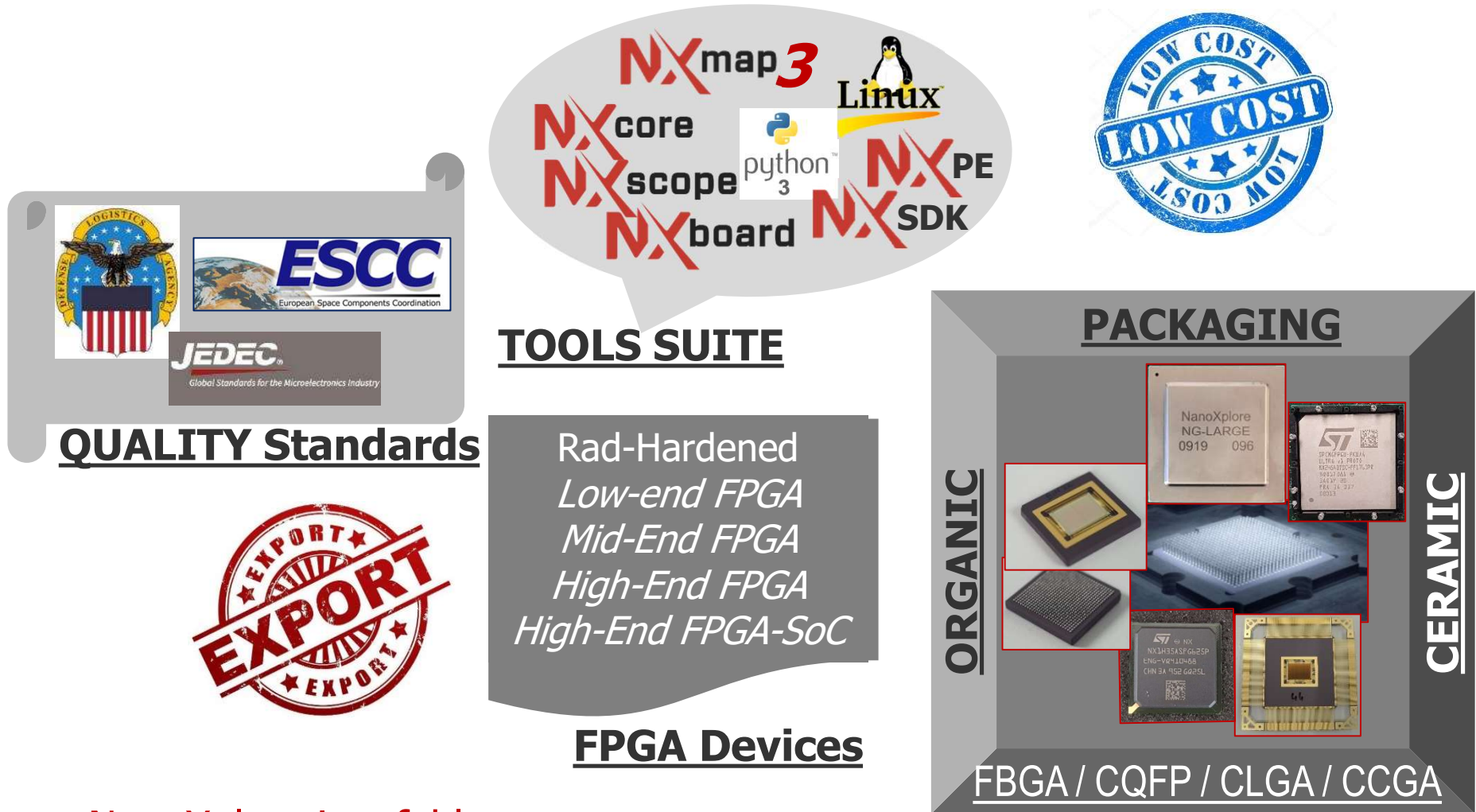


NX RHBD FPGA Product roadmap



Devices	LUT4	RAM	DSP	Hard IP Proc.	HSSL	DDRx	I/Os
NG-Medium	35K	3M	112	N/A	N/A	16DDR2	Up 374
NG-Large	137K	10M	384	ARM-R5	24x 6G	20DDR2	Up 684
NG-Ultra	540K	32M	1344	Full SoC ARM-R52 x4	32x 12G	20DDR3	Up 744
NG-Ultra300	290K	22M	896	N/A	16x 12G	20 DDR3	Up 544

NX Capability Domains



- ◆ NanoXplore is a fabless company

CONCLUSION



NanoXplore brings an answer to ALL SPACE Missions
with **Low-Cost**, **Rad-Hard**, **Low Power** devices

- ◆ From **GEO satellites** requesting
 - *Long life cycle (20years),*
 - *Ceramic/Hermetic packages,*
 - *Low quantity (~few parts),*
 - *Up to Mil-Prf-38535 Class-V qualified,*
 - *At unit price /2 vs Competition*
- ◆ To **Constellation of LEO Satellites** with
 - *Short to Medium life cycle (5 years),*
 - *Organic Packages,*
 - *High quantity: From 100pcs to x1000pcs,*
 - *Military screening & qualification,*
 - *At Unit price like COTS (x100€)*



NX FPGA Supply-Chain



Which FPGA for which Spaceborne Appls



- ◆ Space project classification:
 - Traditional Space
 - or New Space?
- ◆ What about FPGA function?
 - System-On-Chip?
 - Companion chip?
 - Critical function?
- ◆ What about Package type:
 - Ceramic/Hermetic packages?
 - Mean MIL or ESCC standards
 - Organic packages?
 - Mean probably New Space, new standards
- ◆ What about FPGA Quantities & budget?
- ◆ What about Export Control?
- ◆ What about Project planning?

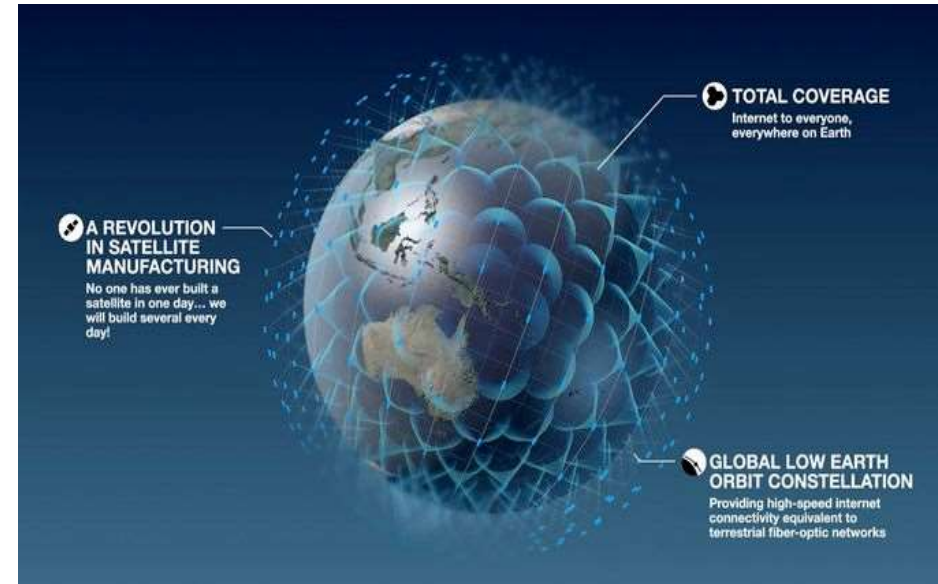


Which FPGA for which Spaceborne Appls



Traditional SPACE

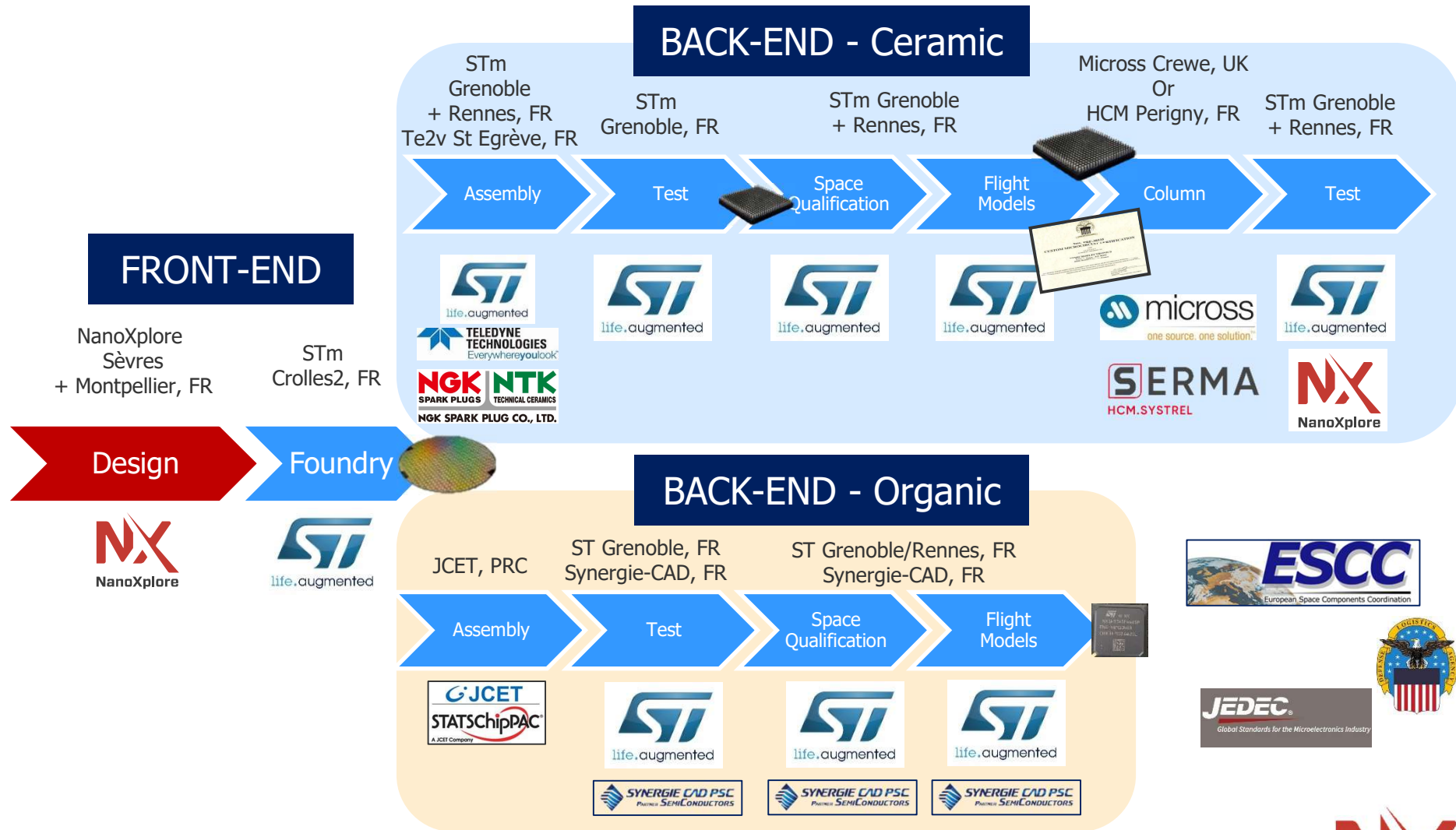
- ◆ Just 1 to 3-5 satellites,
- ◆ Lifecycle: 18 years GEO mission profile,
- ◆ Qty of ICs: **From 2-3units, up x10pcs,**
- ◆ **Ceramic/Hermetic** Packages,
- ◆ QA: ECSS Class-1 or 2,
- ◆ Qualification: At Component level.



NEW SPACE

- ◆ From 100 to x10.000 satellites,
- ◆ Lifecycle: 5-8years LEO mission profile,
- ◆ Qty of ICs: **From 100 to x10Kunits,**
- ◆ **Plastic/Organic** Packages (like COTS),
- ◆ QA: Automotive grade (AEC-Q100),
- ◆ Qualification: At System level.

NX Space Supply-Chain

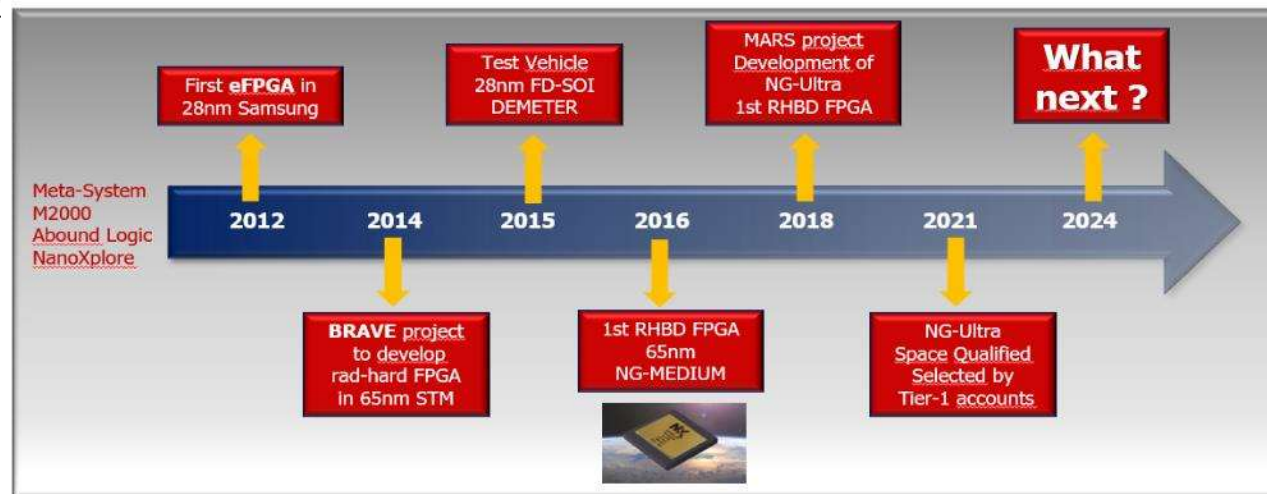
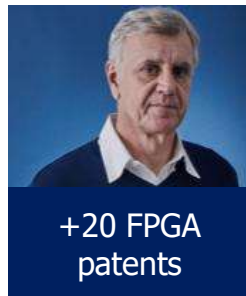


DESIGN – From Low-end to High-End FPGA-SoC

- ◆ NX design based on STRONG technology heritage



Already space
qualified 65nm
FPGA



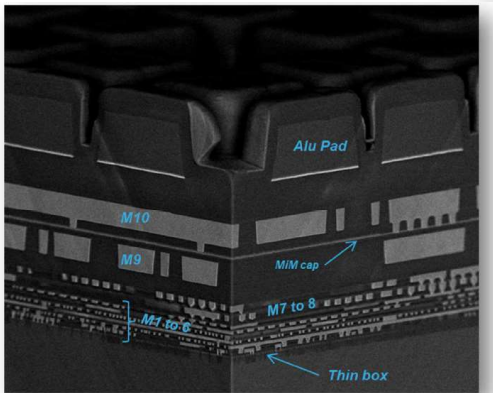
30+ years
experience
engineers

Patented FPGA
Architecture

More than 200
end-users

FOUNDRA – The Complexity is at the interconnect

- ◆ ST foundry – Partnered through the former IBM SemiConductor Development Alliance



28nm FD-SOI Cross Section – STMicroelectronics 2012

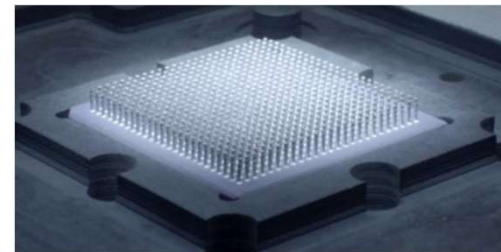


CERAMIC BACK-END

◆ From Rad-Hardened silicon foundry to High-Reliability Ceramic FPGAs.

- ❖ Class-1 EU Assembly lines,
- ❖ Single-Lot Date Code,
- ❖ Full traceability,
- ❖ Ceramic/Hermetic pkgs,
- ❖ High-pin count,
- ❖ IVI capabilities,
- ❖ PRECAP inspection,
- ❖ Data Package,
- ❖ QML / ESCC brand,
- ❖ MOQ – 1piece.

NGK **NTK**
SPARK PLUGS TECHNICAL CERAMICS
NGK SPARK PLUG CO., LTD.



NX Ceramic/Hermetic Quality Flows

Ceramic	PR	M	Q	V
WLAT	✗	✗	✓	✓
TID / Report	✗	✗	✓ Yes	✓ Yes
SLDC	✗	✗	✓	✓
T/C	✗	✗	✓ 10cy	✓ 10cy
IVI	STM policy	2010B SPL	2010B 100%	2010A 100%
Pind-Test	✗	✗	On Request	✓
Serialization	✗	✗	✗	✓
Burn-In	✗	✗	✓ 160h	✓ 240h
PDA	✗	✗	5%	5%
Electrical Test	25°C	-55°C & +125°C	25°C then -55°C & +125°C	25°C then -55°C, +125°C R&R
QCI	✗	✗	✓	✓
EVI	✗	SPL	✓ 100%	✓ 100%
CoC	No Warranty	✗	✓	✓



The documentation and process conversion measures necessary to comply with this revision shall be completed by June 30, 2014.

INCH-POUND

MIL-PRF-38535K
20 December 2013
SUPERSEDING
MIL-PRF-38535J
28 December 2010

PERFORMANCE SPECIFICATION

**INTEGRATED CIRCUITS (MICROCIRCUITS) MANUFACTURING,
GENERAL SPECIFICATION FOR**

Comments, suggestions, or questions on this document should be addressed to: DLA Land and Maritime, ATTN: VAC, P.O. Box 3990, Columbus, OH 43218-3990, or emailed to CMCS@dla.mil. Since contact information can change, you may want to verify the currency of this address information using the ASSIST Online database at <https://assist.dla.mil>.

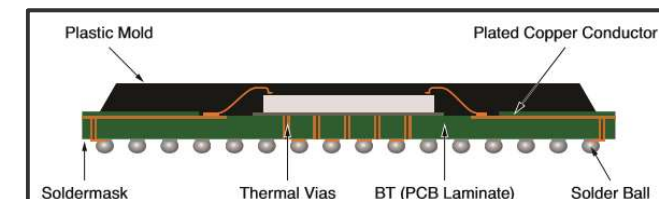
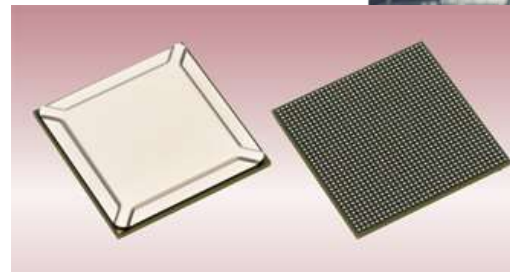
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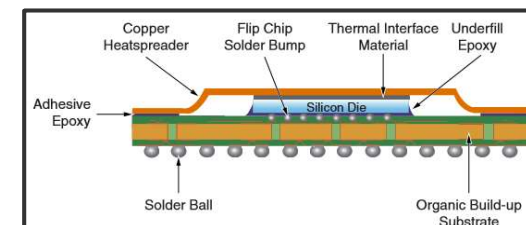
ORGANIC BACK-END

◆ From Rad-Hardened silicon foundry to High-Volume Low-Cost FPGAs

- ❖ Lowest Cost:
 - ❑ OSAT,
- ❖ SnPb / RoHS,
- ❖ Highest Reliability:
 - ❑ JEDEC,
 - ❑ ESCC9000P,
- ❖ Automatic Handlers,
- ❖ Lowest MOQ.



NG medium



NG large

NG ultra

NG ultra



Organic Space Quality Flows

Organic	PR	M	MP	MPS	E
WLAT	✗	✗	✗	Option	✓
TID / Report	✗	✗	✗	Option	✓
SLDC	✗	✗	✗	✓	✓
T/C	✗	✗	10cy	10cy	10cy
IVI	STM policy	2010B SPL	2010B SPL	2010B SPL	2010A 100%
CSAM	✗	✗	✗	✓	✓
Serialization	✗	✗	✗	✗	✓
Burn-In	✗	✗	48h	48h	240h
PDA	✗	✗	✗	✗	5%
Electrical Test	25°C	-55°C & +125°C	+25°C then -55°C & +125°C	+25°C then -55°C & +125°C	25°C then -55°C & +125°C R&R
LAT	✗	✗	✗	✗	✓
EVI	✗	SPL	100%	100%	100%
CoC	No Warranty	✗	✗	✓	✓



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proposes various QA flows from

- **M-grade** for Lowest Cost,
- **MP-grade** where T/C and Burn-In added,
- **MPS-grade** where SLDC and CSAM added,

As well as,

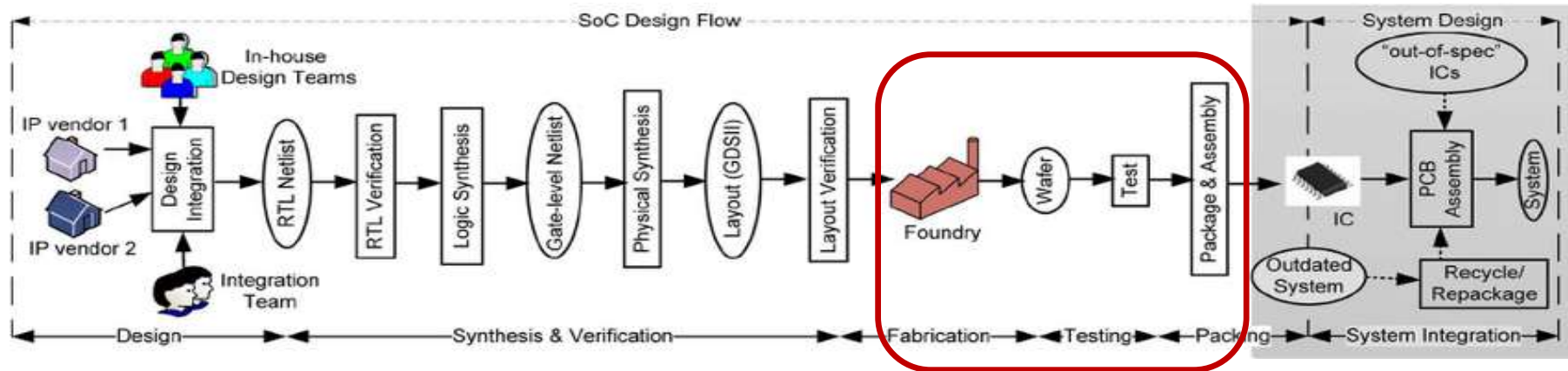
- **E-grade** ~Class1 Organic



NX Leadtimes



NX - Leadtimes



- ◆ NX product leadtimes are subjected to

1. Product status:

- Design validation?
- Device/Package industrialization?
- Military Qualification?
- Space Qualification (ESCC or QML)?

2. Customer forecast?

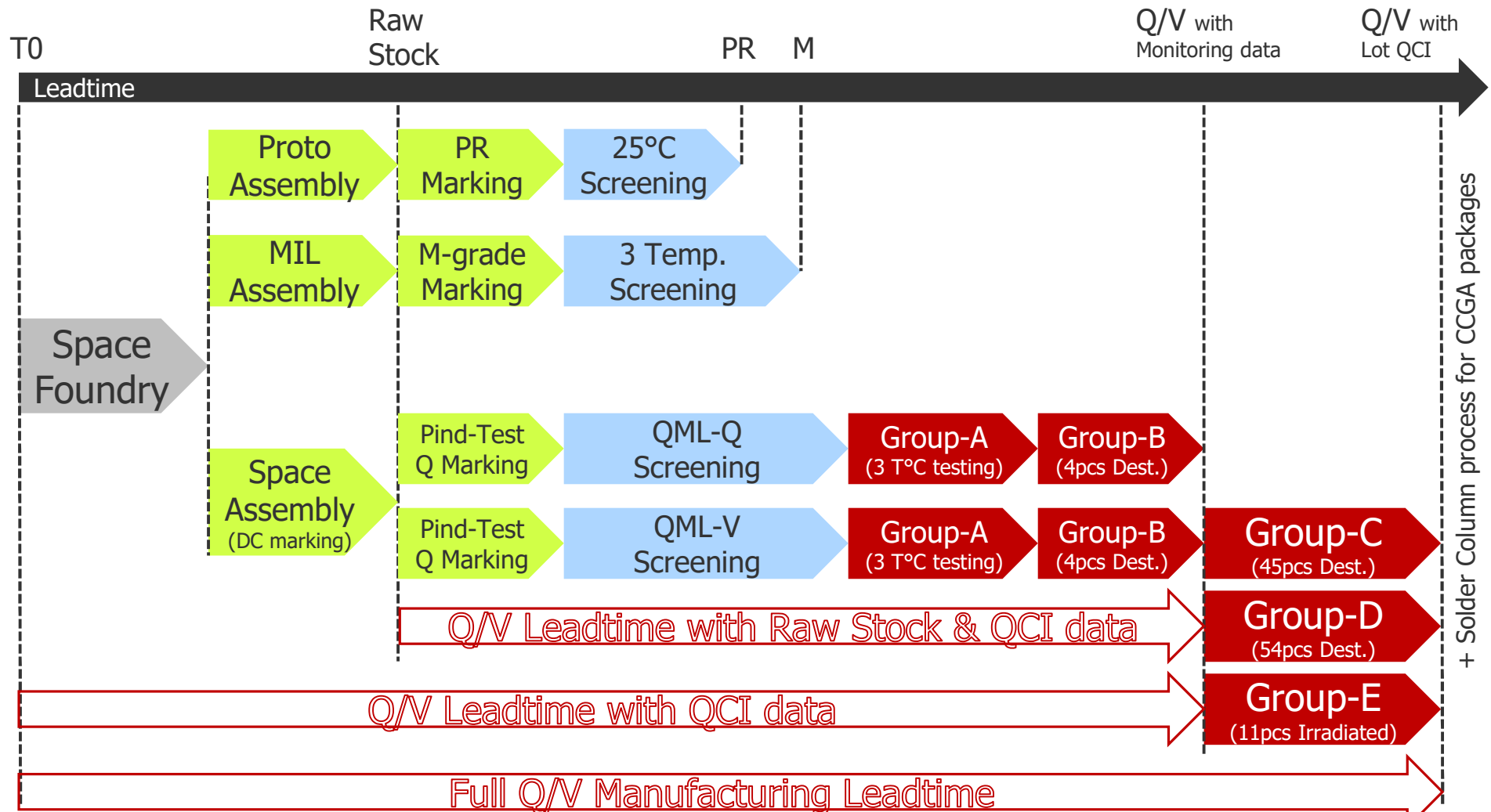
3. Raw material stock:

- Virgin wafers,
- Package piece parts,
- Test board(s),
- Burn-In Board(s),

4. Front-end capacity,

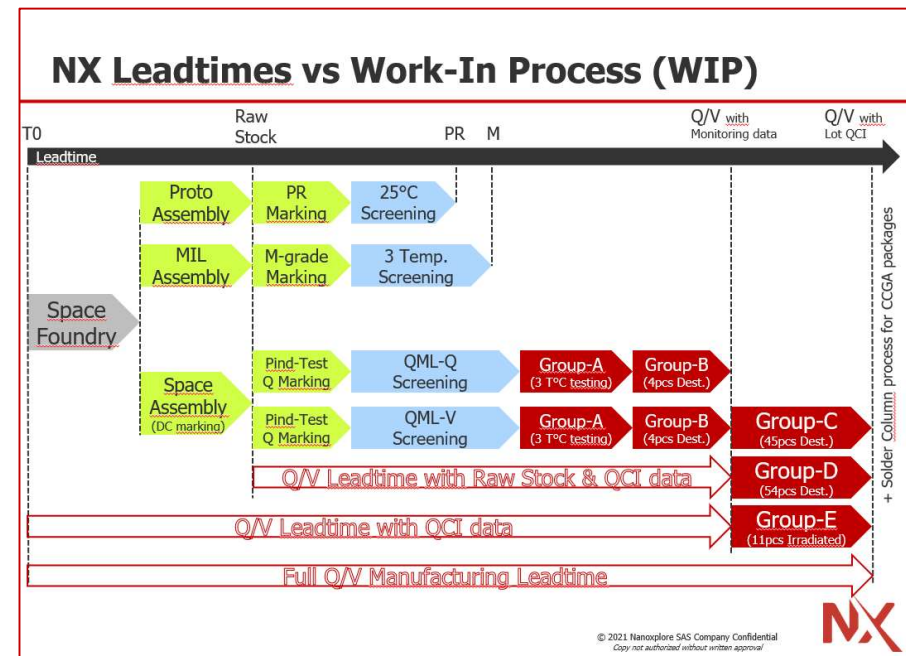
5. Back-end capacity.

NX - Leadtimes vs Work-In Process (WIP)



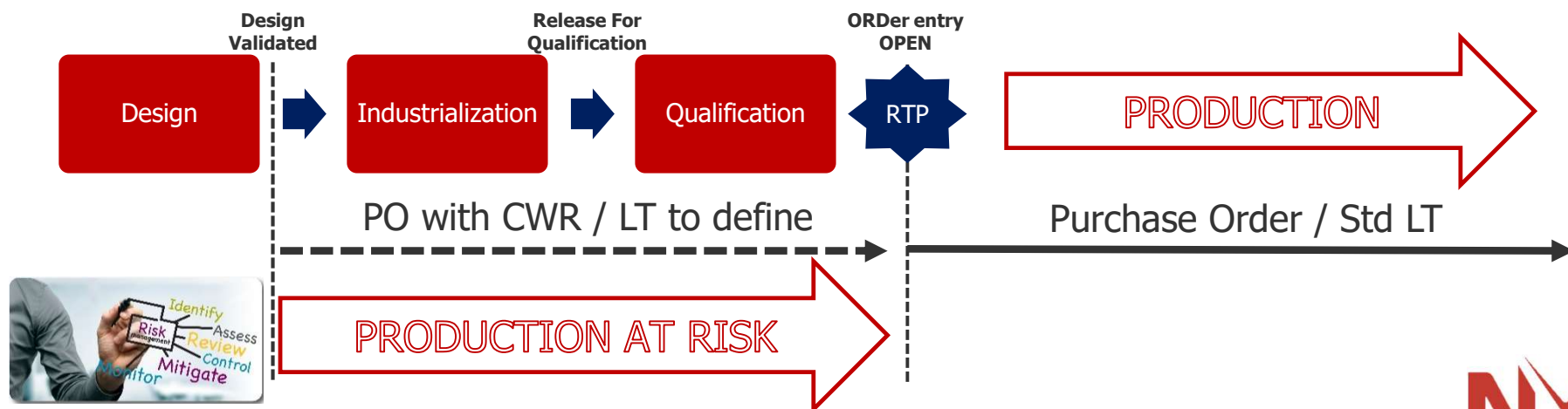
NX - Leadtimes vs Customer Forecast

- ◆ The Customer / Project forecast for EM/EQM/FM parts will allow NX and its supply-chain
 - To launch silicon batche(s),
 - To procure Package piece parts
 - To reserve
 - Assembly capacity
 - Burn-in capacity
 - Test screening capacity
- accordingly,
then to secure and minimize
Manufacturing leadtimes.



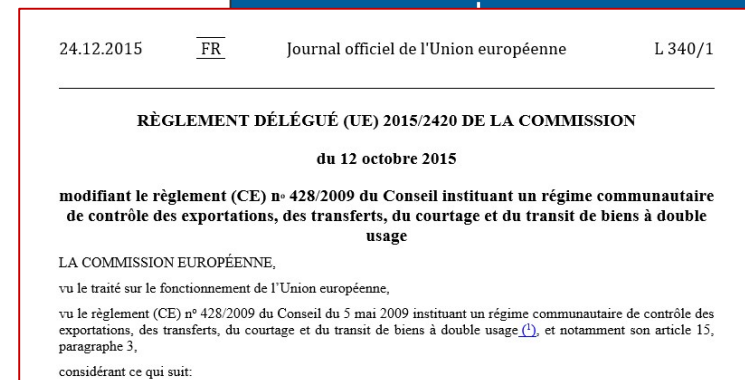
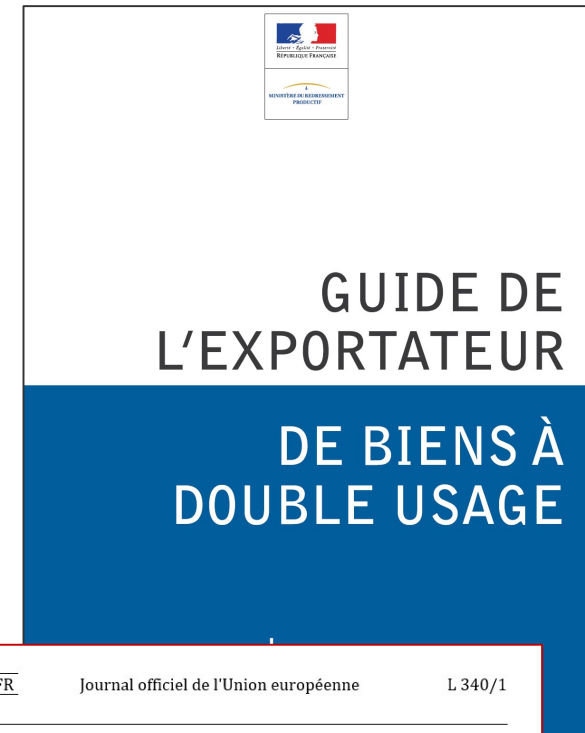
NX - Leadtimes vs Space Qualification

- ◆ NX Production Leadtimes (M to E and V-grades) are valid from T1.
- ◆ T1 is 'ORDER entry Date'.
- ◆ T1 becomes valid when the Release To Production (RTP) is pronounced, I mean when the product is industrialized and qualified.
- ◆ In case a Customer/Project would like to procure a Product before the RTP status, it can be approved by the MFR with a Customer waiver Request (CWR) duly signed by the user. It means, the manufacturing of Goods will be done in parallel with the industrialization-qualification. It will be AT RISK for the Customer.
- ◆ In case the qualification fails, it will require to launch a new batch. The LT will be double.



EU Export Regulation

- ◆ NX products are not subjected to ITAR and EAR because all HW, SW and Documentation have zero links to USA.
- ◆ Nevertheless, we must follow EU 2015/2420 rules about the control of exportations of Dual Use products.
 - ➔ ECCN
(= Export Control Classification Number)
- ◆ ECCNs for Tools and Prototypes
 - NXmap: NOCLASS
 - EKs: NOCLASS
 - Prototypes: NOCLASS
- ◆ ECCNs for Mil&Space Parts: 3A001





NanoXplore

Conclusion



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www.NanoXplore.com

ESCCON-2021 - Abstract

- ◆ After a short introduction of NX FPGA solutions in term of
 - Devices complexity,
 - Package technology,
 - Quality standards,
 - Export regulation,
- ◆ We will identify NX supply-chain versus
 - Requested package type, I mean Ceramic or Organic,
 - Volume,
 - Project planning
 - and Unit Pricesfor either Traditional or New Space projects.
- ◆ The NX supply-chain is based in Europe, being not subjected to export constraints. This is not the case for Low-Cost solutions where Volume organic devices need to be assembled in OSATs mainly based in Asia.

Joël LE MAUFF biography

